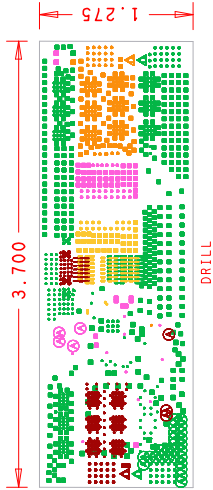
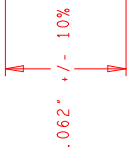


PHYSICAL BOARD DIMENSIONS
& LAYER STRUCTURE

	SILK TOP	silkt.art
	MASK TOP	smaskt.art
	COMPONENT	layer1.art
	LAYER 2	layer2.art
	LAYER 3	layer3.art
	LAYER 4	layer4.art
	LAYER 5	layer5.art
	SOLDER	layer6.art
	MASK BOTTOM	smaskb.art
	SILK BOTTOM	silkb.art



DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	4.0	PLATED	403
⊙	10.0	PLATED	30
.	11.0	PLATED	315
.	12.0	PLATED	504
Δ	41.0	PLATED	4

DRILL CHART: TOP to L2

ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	10.0	PLATED	95
.	11.0	PLATED	49

DRILL CHART: TOP to L3

ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	10.0	PLATED	4
.	11.0	PLATED	1

DRILL CHART: TOP to L4

ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	5.0	PLATED	21
.	10.0	PLATED	81
.	12.0	PLATED	106

DRILL CHART: L3 to BOTTOM

ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
⊙	10.0	PLATED	3

DRILL CHART: L5 to BOTTOM

ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	10.0	PLATED	52

DRILL CHART: L6 to BOTTOM

ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	10.0	PLATED	4

DRILL CHART: L7 to BOTTOM

ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	10.0	PLATED	31

NOTES:

1. THIS BOARD IS RoHS COMPLIANT.
2. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW WITH THE REQUIREMENTS OF IPC-D-275 AND IPC-A-600.
3. MATERIAL: FR4 (RoHS COMPLIANT), 2 OZ COPPER OUTER / 1OZ. INNER LAYERS
4. APPLY SOLDER MASK, BOTH SIDES OVER BARE COPPER IAW IPC-SM-840. CLASS 2 (LPI) (BLUE MASK).
5. ALL PATTERNS ARE VIEWED FROM THE PRIMARY SIDE LOOKING THROUGH THE BOARD.
6. UNLESS OTHERWISE SPECIFIED ALL HOLE DIAMETERS ARE AFTER PLATING.
7. APPLY SILKSCREEN USING WHITE NON-CONDUCTIVE EPOXY BASED INK.
8. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY. USE NETLIST PROVIDED ISL73847MDEM02ZA IPC356, IPC IAW IPC-D-356.
9. MARK DATE CODE AND MANUFACTURES IDENTIFICATION ON SOLDER SIDE PER IPC-6011 AND IPC-6012.
10. TOLERANCE ON ALL DRILL HOLES SHALL BE IAW IPC-D-2221 & 2222 UNLESS OTHERWISE SPECIFIED.
11. ALL 4 MIL and 11 MIL VIA'S ARE TO BE NON-CONDUCTIVE EPOXY FILLED AND CAPPED.
12. PLEASE KEEP OR SILKSCREEN THE INTERSIL LOGO ON BOARD. DO NOT SWITCH TO RENESASD LOGO ON THIS BOARD.

Drawn By:	Date Drawn:	Engineer:
Tim Klemann	05/17/2023	Juan Garcia
Released By:	Date Released:	ISL73847M DEM02 Board Layout
Updated By:	Date Updated:	
		MASK#
		HDWR ID
		REV.
		A
FILENAME:		SHEET
\\ISL73847M\ISL73847MDEM02ZA		1 of 1